

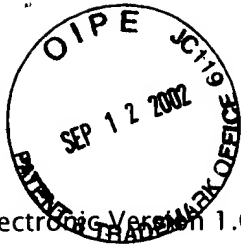


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Electronic Patent Application Submission  
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EFS ID: 17836  
Application ID: 09982855  
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ETCH STOP AND DIFFUSION  
BARRIER  
First Named Inventor: Richard Metzler  
Domestic/Foreign Application: Domestic Application  
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## SIDEWALLS AS SEMICONDUCTOR ETCH STOP AND DIFFUSION BARRIER

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First Named Inventor: Richard A. Metzler

### SUBMITTED BY

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### Attached Files:

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